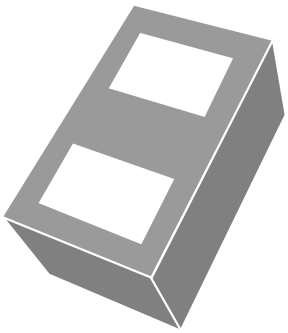
ESDAVLC5-1BF4

Low clamping, very low capacitance bidirectional single line ESD protection

Datasheet - production data



0201 package

Features

- Low clamping voltage
- Bidirectional device
- Low leakage current
- 0201 package
- Ultra low PCB area: 0.18 mm^2
- ECOPACK®2 compliant component

Complies with the following standards

- IEC 61000-4-2 level 4 (exceed level 4):
  - ±30 kV (air discharge)
  - ±12 kV (contact discharge)

Applications

Where transient over voltage protection in ESD sensitive equipment is required, such as:

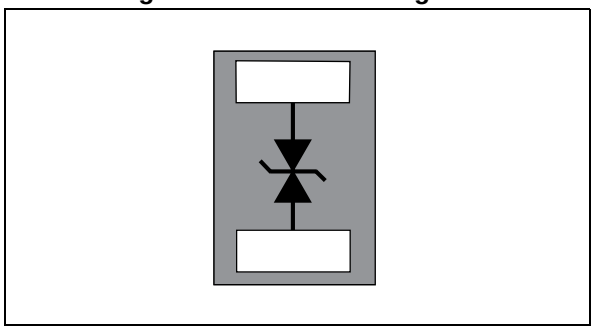
- Smartphones, mobile phones and accessories
- Tablets, PCs, netbooks and notebooks
- Portable multimedia devices and accessories
- Digital cameras and camcorders
- Communication and highly integrated systems

Description

The ESDAVLC5-1BF4 is a bidirectional single line TVS diode designed to protect the data line or other I/O ports against ESD transients.

The device is ideal for applications where both reduced line capacitance and board space saving are required.

Figure 1. Functional diagram



This is information on a product in full production. www.st.com

1 Characteristics

Table 1. Absolute maximum ratings

Symbol	Parameter		Value	Unit
V_{PP} (1)	Peak pulse voltage	IEC 61000-4-2 contact discharge IEC 61000-4-2 air discharge	±12 ±30	kV
P_{PP}(1)	Peak pulse power (8/20 µs)		20	W
I_{PP}(1)	Peak pulse current (8/20 µs)		±1.7	A
T_j	Operating junction temperature range		-55 to 150	°C
T_{stg}	Storage temperature range		-65 to +150	°C
T_L	Maximum lead temperature for soldering during 10 s		260	°C

1. For a surge greater than the maximum values, the diode will fail in short-circuit.

Figure 2. Electrical characteristics (definitions)

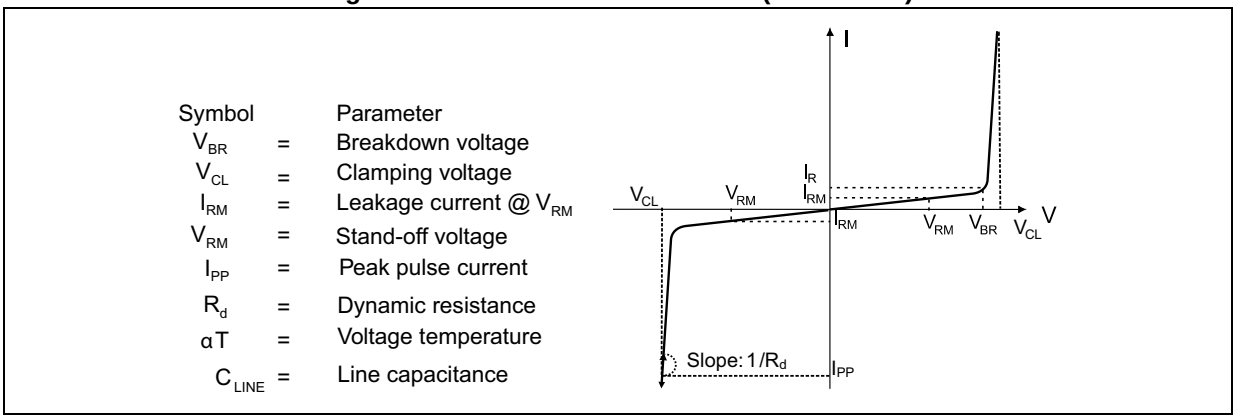


Table 2. Electrical characteristics (values, T_{amb} = 25 °C)

Symbol	Test conditions	Test conditions	Value			Unit
			Min.	Typ.	Max.	
V_{BR}	Breakdown voltage	I_R = 1 mA	5.8		8.5	V
V_{RM}	Working voltage		-5.3		5.3	V
I_{RM}	Leakage current	V_{RM} = ±5.3 V			100	nA
C_{LINE}	Line capacitance	V_{LINE}= 0 V, F = 1 MHz, V_{OSC} = 30 mV			7	pF
V_{CL}	Clamping voltage	I_{PP} = 1.7 A- 8/20			11.7	V
V_{CL}	Clamping voltage	IEC 61000-4-2, measured at 30 ns		16.3		V
V_{CL}	Clamping voltage	TLP measurement (pulse durantion 100 ns), I_{PP} = 16 A		19.2		V
R_D	Dynamic resistance	Pulse durantion 100 ns(1)		0.67		Ω
F_C	Cut-off frequency	-3dB		1.5		GHz

1. More information is available in the application note: AN4022, TVS short pulse dynamic resistance measurement and correlation with TVS clamping voltage during ESD.

Figure 3. Leakage current versus junction temperature (typical values)

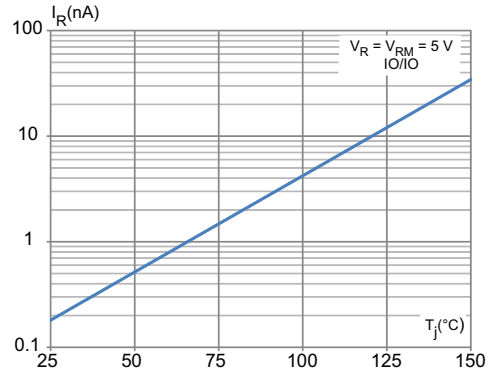


Figure 4. Junction capacitance versus applied voltage (typical values)

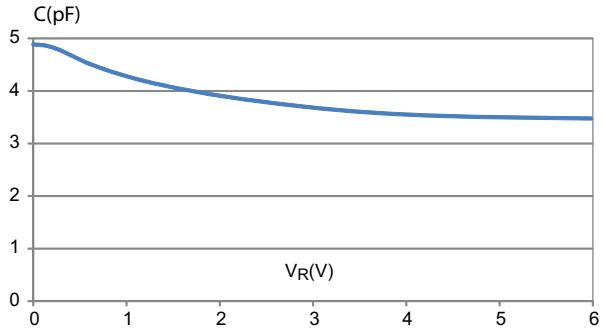


Figure 5. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

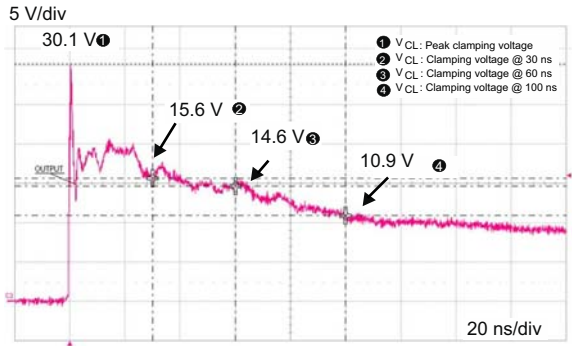


Figure 6. ESD response to IEC 61000-4-2 (-8 kV contact discharge)

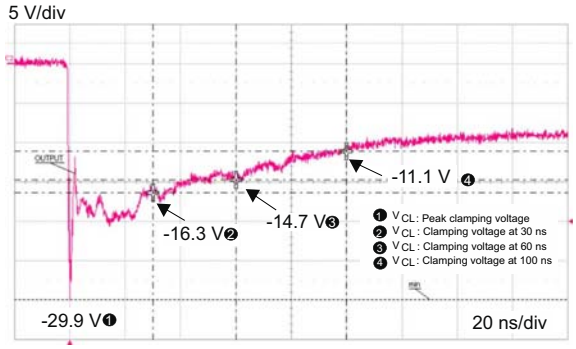


Figure 7. S21 attenuation

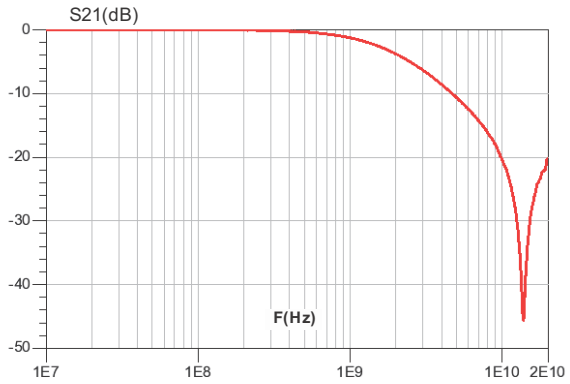
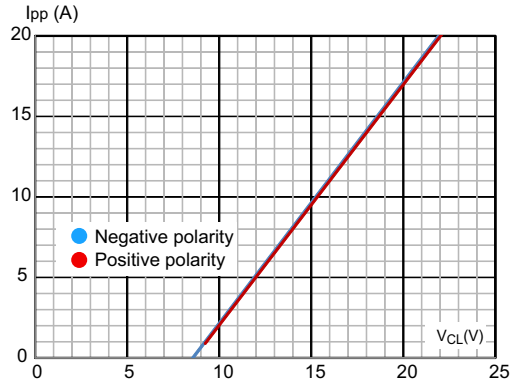


Figure 8. TLP measurementst



2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

2.1 0201 package information

Figure 9. 0201 package outline

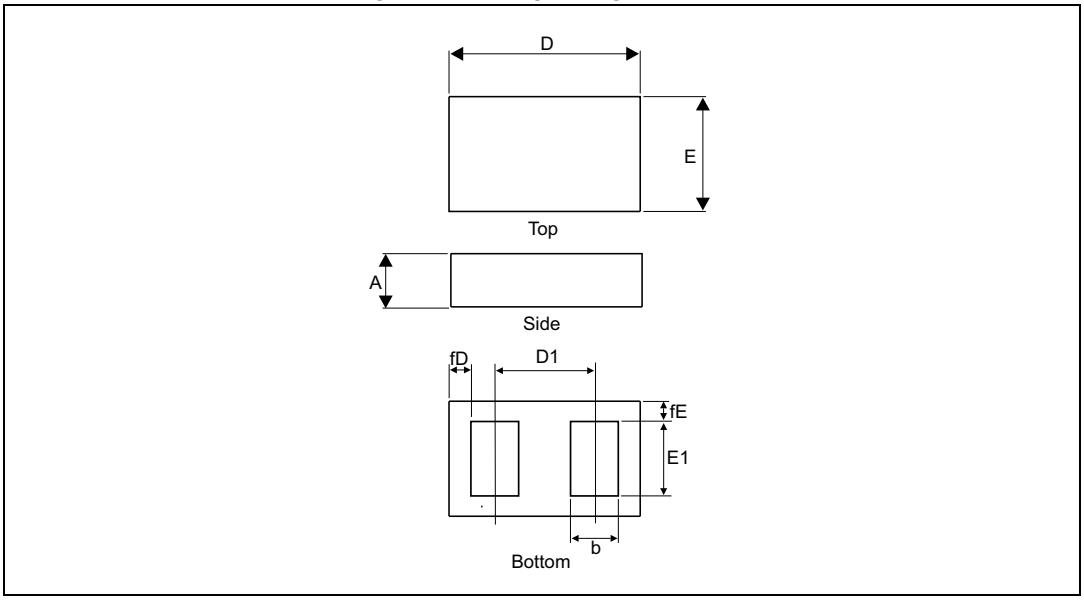


Table 3. 0201 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.28	0.3	0.32	0.0110	0.0118	0.0126
b	0.125	0.14	0.155	0.0049	0.0055	0.0061
D	0.57	0.6	0.63	0.0224	0.0236	0.0248
D1		0.35			0.0138	
E	0.27	0.3	0.33	0.0106	0.0118	0.0130
E1	0.175	0.19	0.205	0.0069	0.0075	0.0081
fD	0.11	0.125	0.14	0.0043	0.0049	0.0055
fE	0.04	0.055	0.07	0.0016	0.0022	0.0028

Figure 10. Footprint in mm (inches)

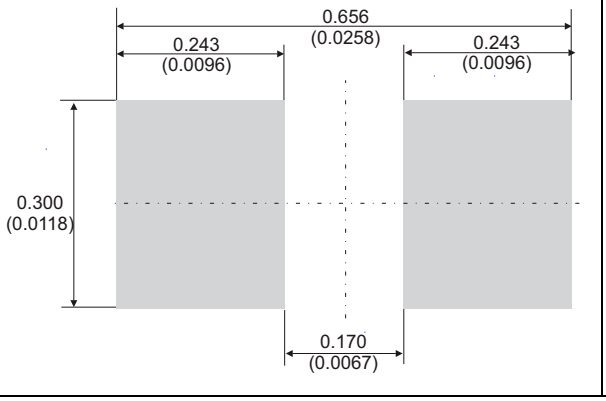
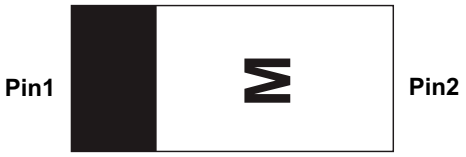


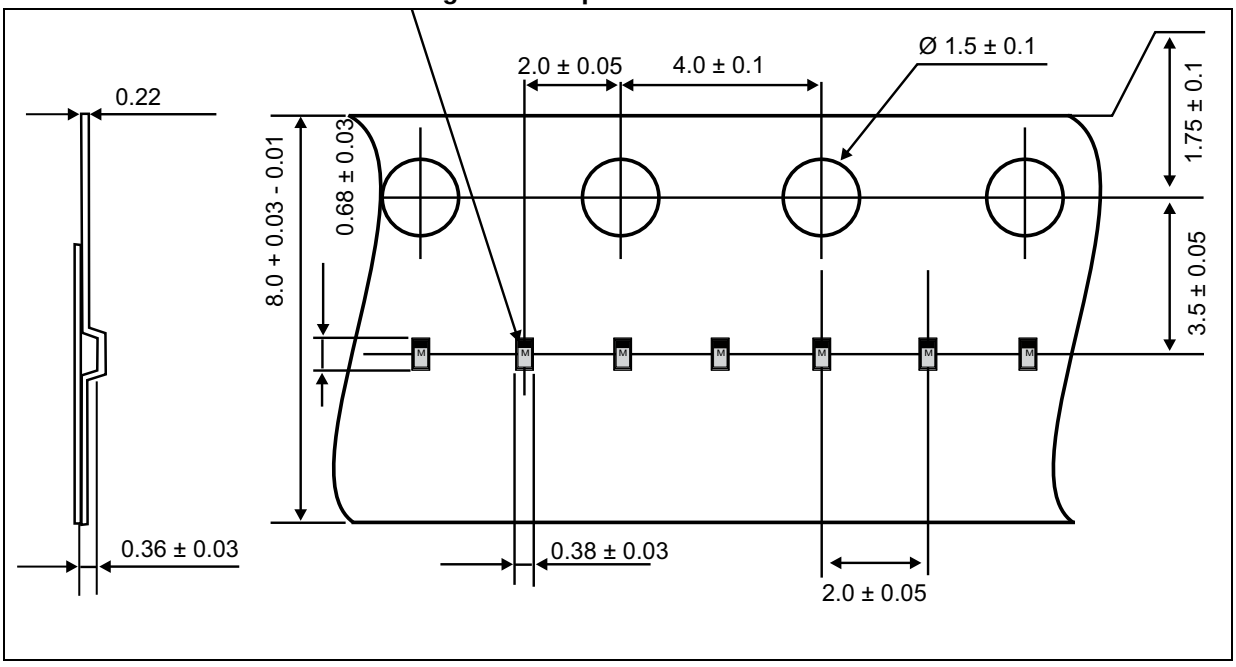
Figure 11. Marking



Note: The marking codes can be rotated by 90° or 180° to differentiate assembly location.In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

2.2 Packing information

Figure 12. Tape and reel outline

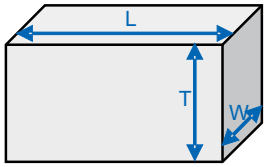


3 Recommendation on PCB assembly

3.1 Stencil opening design

1. General recommendations on stencil opening design
   a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

Figure 13. Stencil opening dimensions



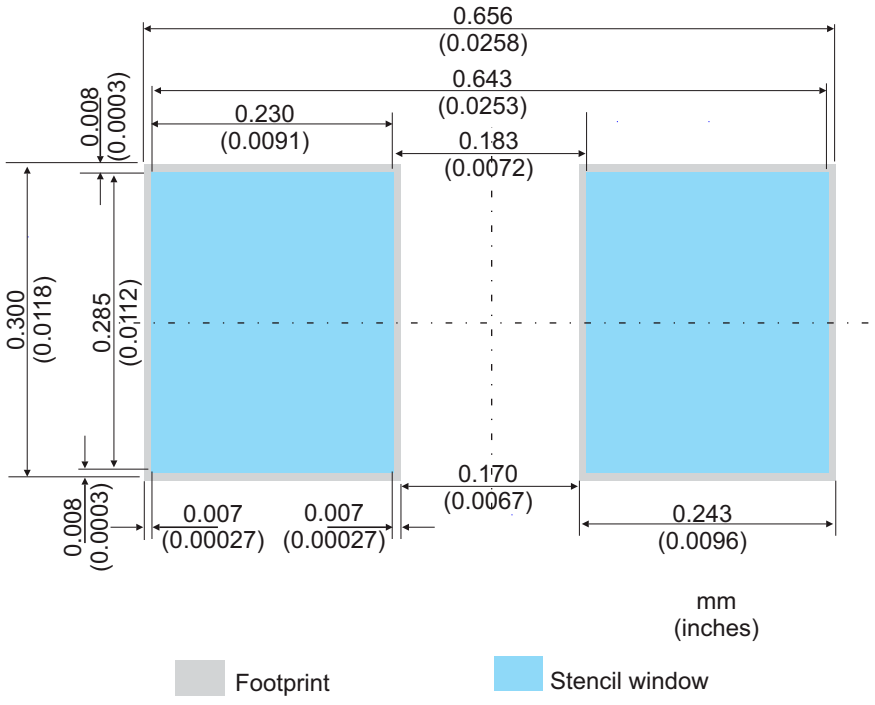
   b) General design rule
   Stencil thickness (T) = 75 ~ 125 µm

$$\text{Aspect Ratio} = \frac{W}{T} \geq 1.5$$

$$\text{Aspect Area} = \frac{L \times W}{2T(L + W)} \geq 0.66$$

2. Recommended stencil window
   a) Stencil opening thickness: 80 µm
   b) Other dimensions: see *Figure 14*

Figure 14. Recommended stencil window position, stencil opening thickness: 80 µm



3.2 Solder paste

1. Use halide-free flux, qualification ROL0 according to ANSI/J-STD-004.
2. “No clean” solder paste recommended.
3. Offers a high tack force to resist component displacement during PCB movement.
4. Use solder paste with fine particles: Type 4 (powder particle size 20-48 µm per IPC J STD-005).

3.3 Placement

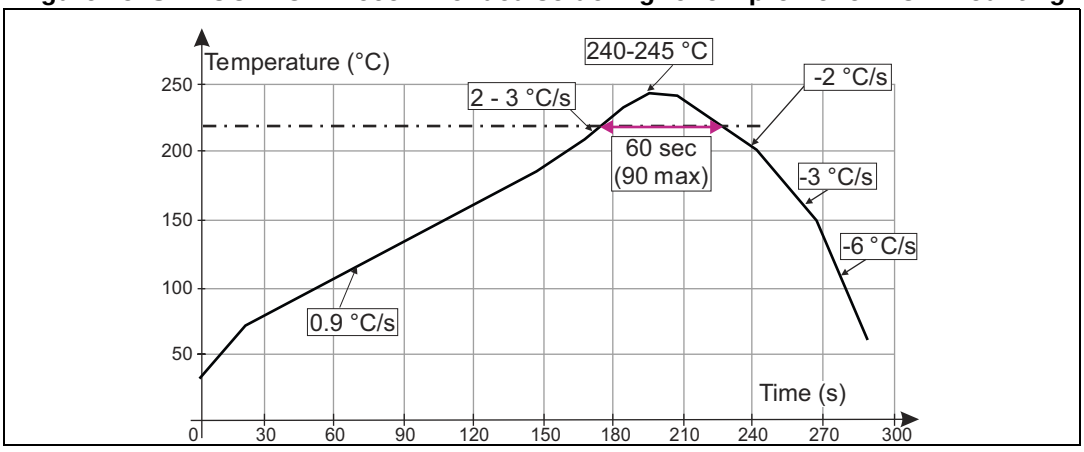
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering.
3. Standard tolerance of ± 0.05 mm is recommended.
4. 1.0 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

3.5 Reflow profile

Figure 15. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.

4 Ordering information

Figure 16. Ordering information scheme

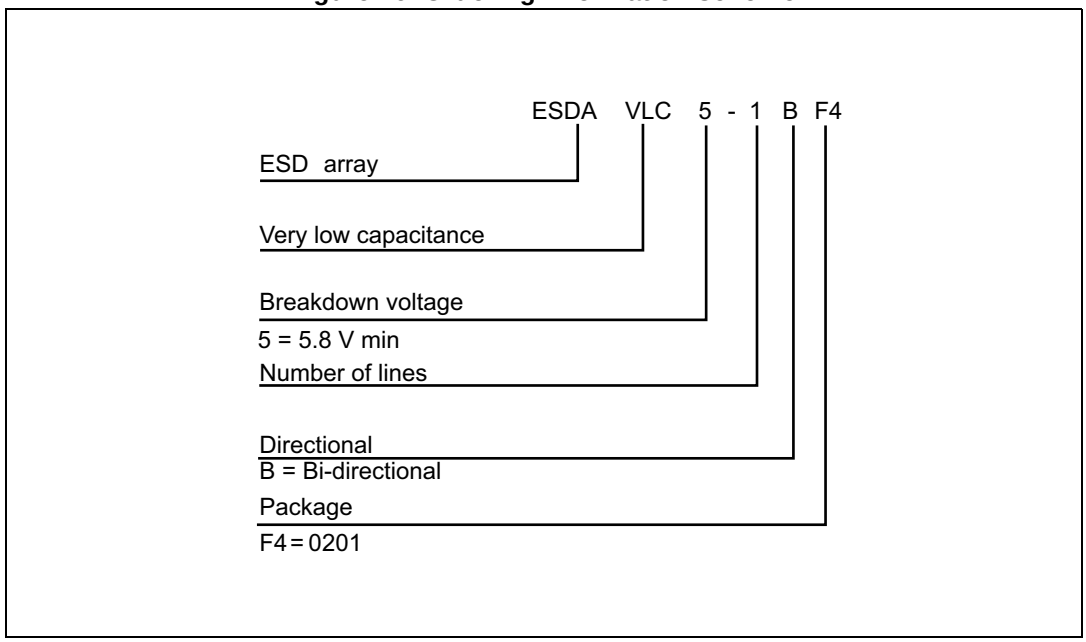


Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDAVLC5-1BF4	M(1)	0201	0.116 mg	15000	Tape and reel

1. The marking codes can be rotated by 90° or 180° to differentiate assembly location

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
15-Oct-2015	1	First issue

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